

Power Management Switch ICs for PCs and Digital Consumer Products



Load Switch ICs for Portable Equipment

BD6528HFV, BD6529GUL

No.11029ECT19

●Description

Power switch for memory card Slot (BD6528HFV, BD6529GUL) is a high side switch IC having one circuit of N-channel Power MOSFET. This switch IC achieves ON resistance of 100mΩ with BD6529GUL; and 110mΩ with BD6528HFV. Operations from low input voltage ($V_{IN} \leq 2.7V$) is possible; made for use of various switch applications. BD6524HFV is available in a space-saving HVSO6 package. BD6529GUL is available in a space-saving VCSP-6 package.

●Features

- 1) Single channel of Low On-Resistance (Typ. = 100mΩ) N-channel MOSFET built in
- 2) 500mA output current
- 3) Low voltage switch capability
- 4) Soft-start function
- 5) Output discharge circuit
- 6) Reverse current flow blocking at switch off
- 7) HVSO6 package for BD6528HFV
VCSP50L1 package for BD6529GUL

●Applications

Memory card slots of Mobile phone, Digital still camera, PDA, MP3 player, PC, etc.

●Line up matrix

Part Number	ON resistance	Output current	Discharge circuit	Logic Control Input	Package
BD6528HFV	110mΩ	500mA	○	High	HVSO6 1.6 x 3.0 mm
BD6529GUL	100mΩ	500mA	○	High	VCSP50L1 1.5 x 1.0 mm

●Absolute maximum ratings

Parameter	Symbol	Ratings	Unit
Supply voltage	V_{DD}	-0.3 ~ 6.0	V
V_{IN} voltage	V_{IN}	-0.3 ~ 6.0	V
V_{EN} voltage	V_{EN}	-0.3 ~ $V_{DD} + 0.3$	V
V_{OUT} voltage	V_{OUT}	-0.3 ~ 6.0	V
Storage temperature	T_{STG}	-55 ~ 150	°C
Power dissipation	P_d	849 *1 (BD6528HFV)	mW
		575 *2 (BD6529GUL)	

*1 Mounted on 70mm * 70mm * 1.6mm Glass-epoxy PCB. Derating: 6.8mW / °C at $T_a > 25^\circ\text{C}$

*2 Mounted on 50mm * 58mm * 1.75mm Glass-epoxy PCB. Derating: 4.6mW / °C at $T_a > 25^\circ\text{C}$

* This product is not designed for protection against radioactive rays.

* Operation is not guaranteed.

●Operating conditions

Parameter	Symbol	Ratings			Unit
		Min.	Typ.	Max.	
Operating voltage	V_{DD}	2.7	3.3	4.5	V
Switch input voltage	V_{IN}	0	1.2	2.7	V
Operation temperature	T_{OPR}	-25	25	85	°C
Output current	I_{LO}	0	-	500	mA

●Electrical characteristics

OBD6528HFV(unless otherwise specified, $V_{DD} = 3.3V$, $V_{IN} = 1.2V$, $T_a = 25^{\circ}C$)

Parameter	Symbol	Limits			Unit	Condition
		Min.	Typ.	Max.		
[Current consumption]						
Operating current	I _{DD}	-	20	30	μA	V _{EN} = 1.2V
Standby current	I _{STB}	-	0.01	1	μA	V _{EN} = 0V
[I/O]						
EN input voltage	V _{ENH}	1.2	-	-	V	High level input
	V _{ENL}	-	-	0.4	V	Low level input
EN input current	I _{EN}	-1	-	1	μA	V _{EN} = 0V or V _{EN} = 1.2V
[Power switch]						
On-resistance	R _{ON}	-	110	-	mΩ	I _{OUT} = 500mA
Switch leakage current	I _{LEAK}	-	0.01	10	μA	V _{EN} = 0V, V _{OUT} = 0V
Output rise time	T _{ON1}	-	0.5	1	ms	R _L = 10Ω, V _{OUT} 10% → 90%
Output turn-on time	T _{ON2}	-	0.6	2	ms	R _L = 10Ω, V _{EN} High →V _{OUT} 90%
Output fall time	T _{OFF1}	-	1	20	μs	R _L = 10Ω, V _{OUT} 90% → 10%
Output turn-off time	T _{OFF2}	-	15	100	μs	R _L = 10Ω, V _{EN} Low →V _{OUT} 10%
[Discharge circuit]						
Discharge on-resistance	R _{DISC}	-	70	110	Ω	I _{OUT} = -1mA, V _{EN} = 0V
Parameter	I _{DISC}	-	15	20	mA	V _{OUT} = 3.3V, V _{EN} = 0V

OBD6529GUL(unless otherwise specified, $V_{DD} = 3.3V$, $V_{IN} = 1.2V$, $T_a = 25^{\circ}C$)

Parameter	Symbol	Limits			Unit	Condition
		Min.	Typ.	Max.		
[Current consumption]						
Operating current	I _{DD}	-	20	30	μA	V _{EN} = 1.2V
Standby current	I _{STB}	-	0.01	1	μA	V _{EN} = 0V
[I/O]						
EN input voltage	V _{ENH}	1.2	-	-	V	High level input
	V _{ENL}	-	-	0.4	V	Low level input
EN input current	I _{EN}	-1	-	1	μA	V _{EN} = 0V or V _{EN} = 1.2V
[Power switch]						
On Resistance	R _{ON}	-	100	-	mΩ	I _{OUT} = 500mA
Switch leakage current	I _{LEAK}	-	0.01	10	μA	V _{EN} = 0V, V _{OUT} = 0V
Output turn on rise time	T _{ON1}	-	0.5	1	ms	R _L = 10Ω, V _{OUT} 10% → 90%
Output turn on time	T _{ON2}	-	0.6	2	ms	R _L = 10Ω, V _{EN} High →V _{OUT} 90%
Output turn off fall time	T _{OFF1}	-	0.1	4	μs	R _L = 10Ω, V _{OUT} 90% → 10%
Output turn off time	T _{OFF2}	-	1	6	μs	R _L = 10Ω, V _{EN} Low →V _{OUT} 10%
[Discharge circuit]						
Discharge on-resistance	R _{DISC}	-	70	110	Ω	I _{OUT} = -1mA, V _{EN} = 0V
Discharge current	I _{DISC}	-	15	20	mA	V _{OUT} = 3.3V, V _{EN} = 0V

●Test circuit

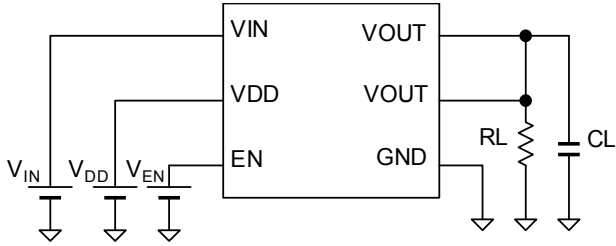


Fig.1 Measurement circuit

●Switch output turn ON/OFF timing

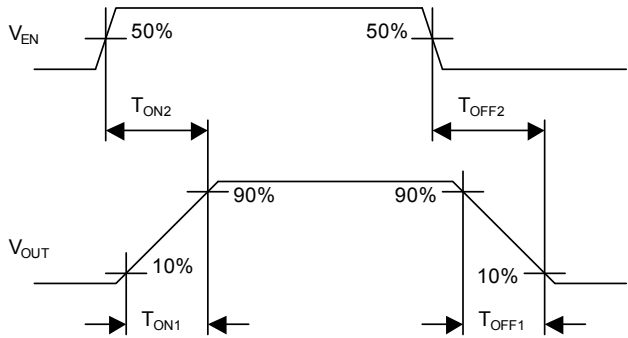


Fig.2 Timing diagrams

●Reference data

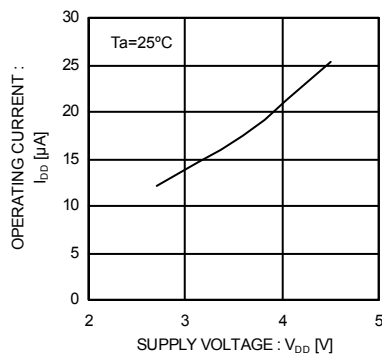
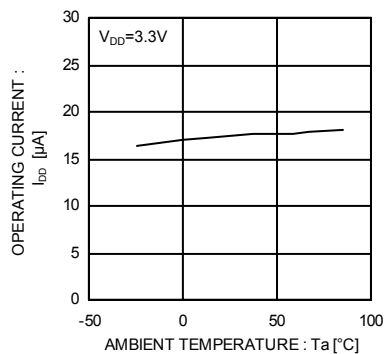
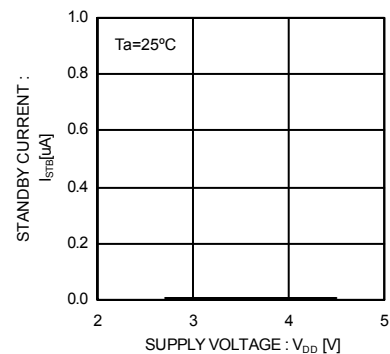
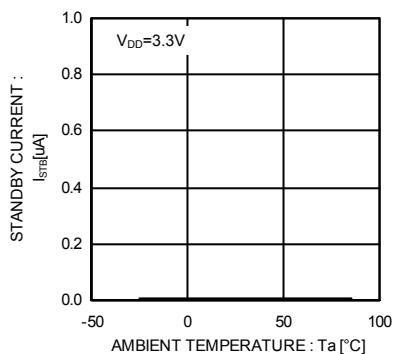
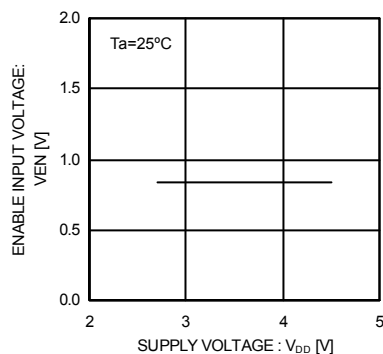
Fig.3 Operating current
EN enableFig.4 Operating current
EN enableFig.5 Standby current
EN disableFig.6 Standby current
EN disable

Fig.7 EN input voltage

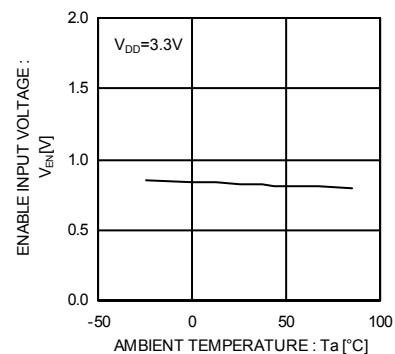
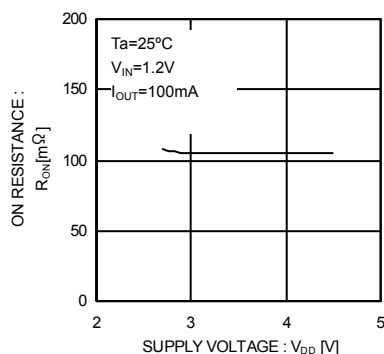
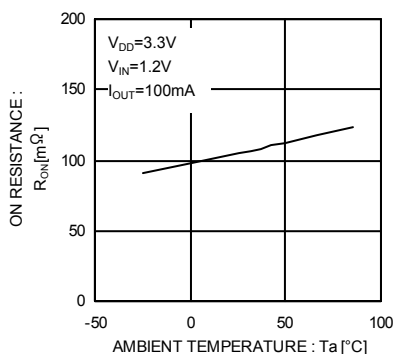
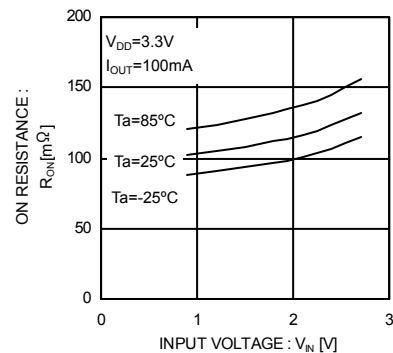
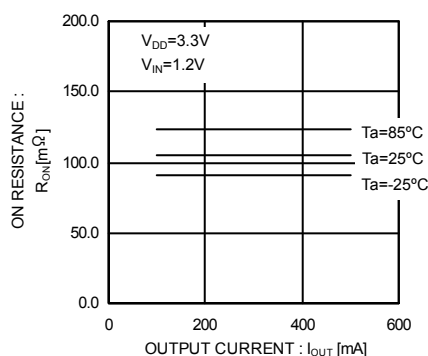
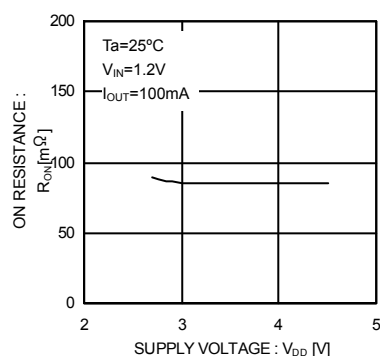
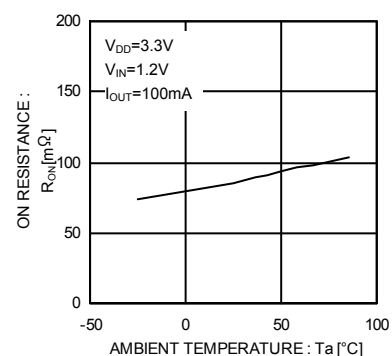


Fig.8 EN input voltage

Fig.9 On-resistance vs. V_{DD}
(BD6528HFV)Fig.10 On-resistance vs. temperature
(BD6528HFV)Fig.11 On-resistance vs. V_{IN}
(BD6528HFV)Fig.12 On-resistance vs. I_{OUT}
(BD6528HFV)Fig.13 On-resistance vs. V_{DD}
(BD6529GUL)Fig.14 On-resistance vs. temperature
(BD6529GUL)

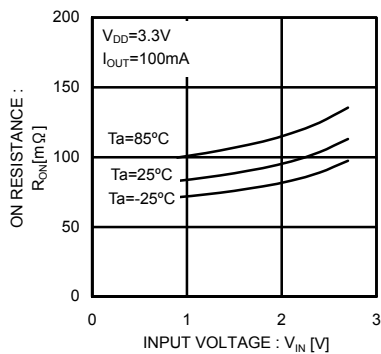


Fig.15 On-resistance vs. V_{IN} (BD6529GUL)

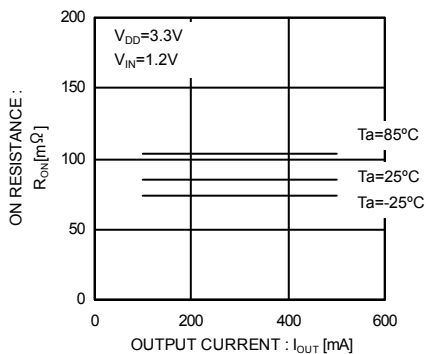


Fig.16 On-resistance vs. I_{OUT} (BD6529GUL)

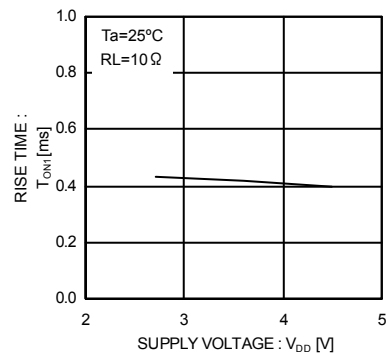


Fig.17 Output rise time

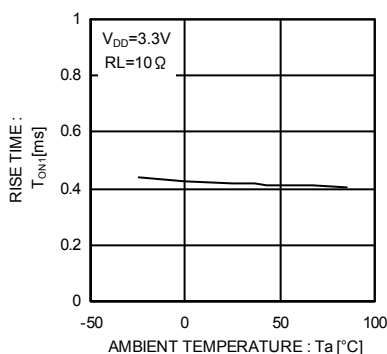


Fig.18 Output rise time

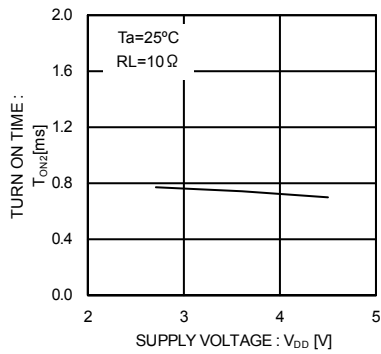


Fig.19 Output turn-on time

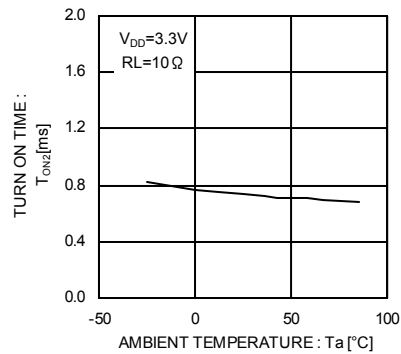


Fig.20 Output turn-on time

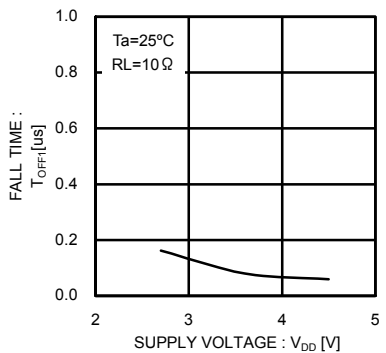


Fig.21 Output fall time

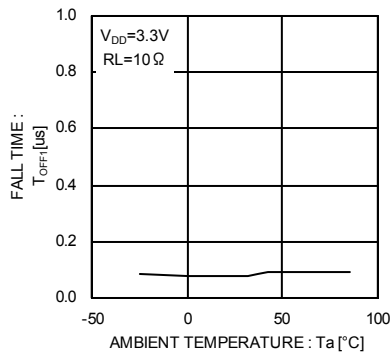


Fig.22 Output fall time

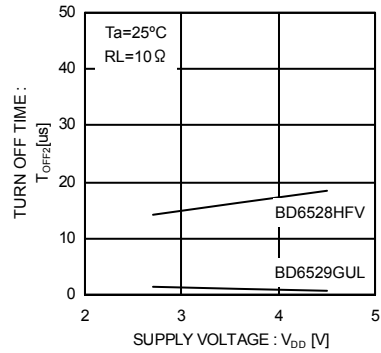


Fig.23 Output turn-off time

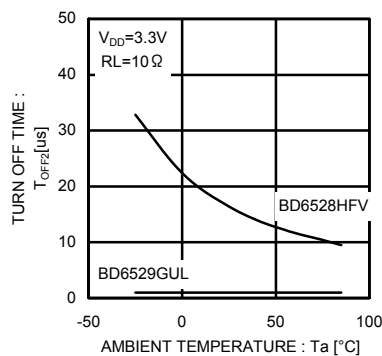


Fig.24 Output turn-off time

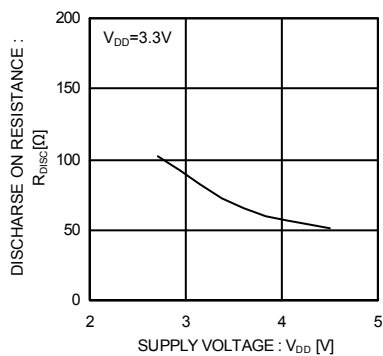


Fig.25 Discharge on-resistance

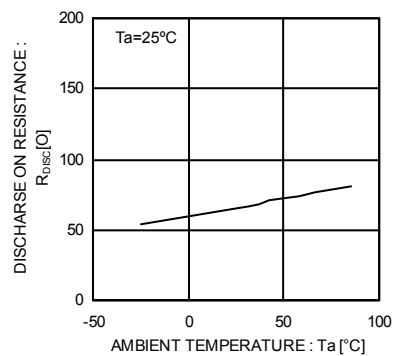


Fig.26 Discharge on-resistance

●Waveform data

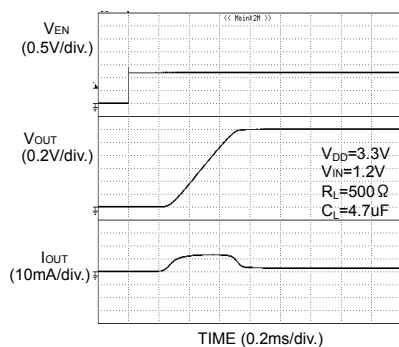


Fig.27 Output turn-on response
BD6528HFV

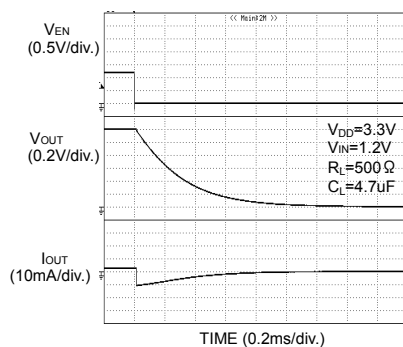


Fig.28 Output turn-off response
BD6528HFV

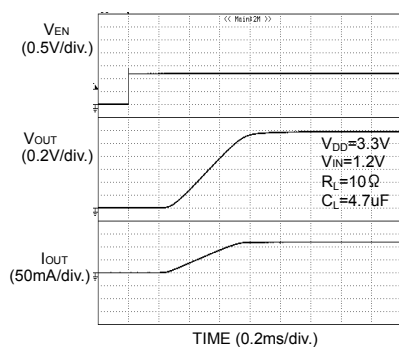


Fig.29 Output turn-on response
BD6528HFV

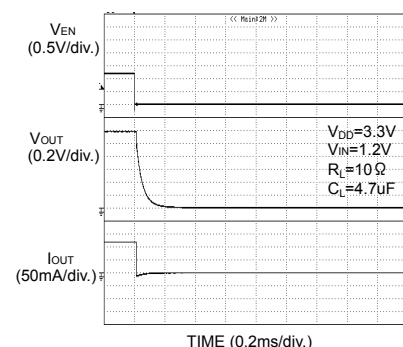


Fig.30 Output turn-off response
BD6528HFV

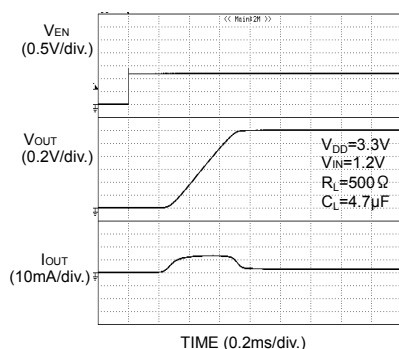


Fig.31 Output turn-on response
BD6529GUL

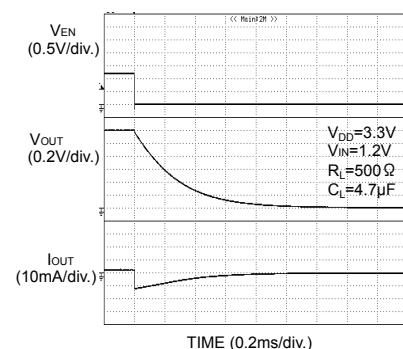


Fig.32 Output turn-off response
BD6529GUL

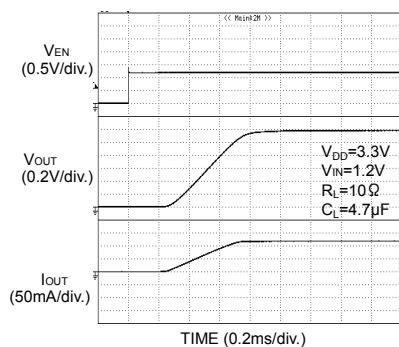


Fig.33 Output turn-on response
BD6529GUL

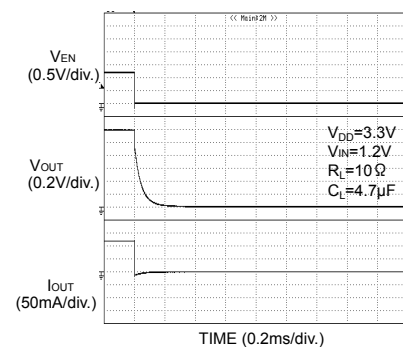


Fig.34 Output turn-off response
BD6529GUL

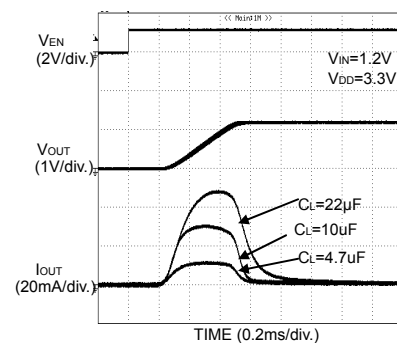


Fig.35 Rush current response

●Block diagram

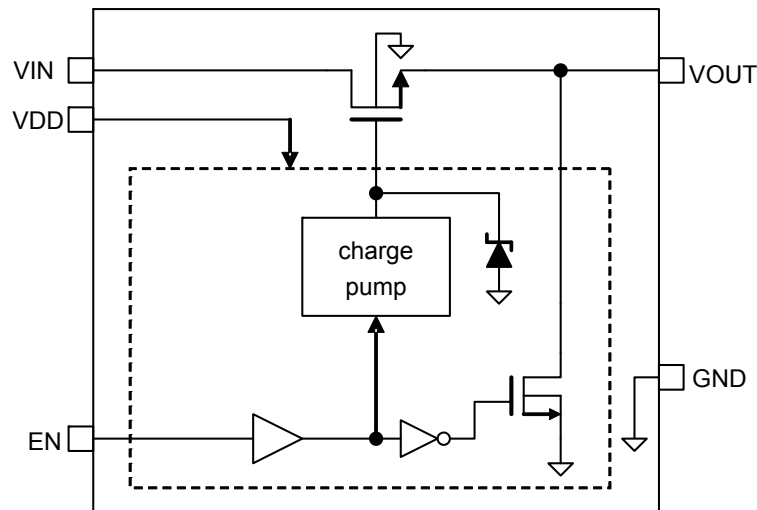
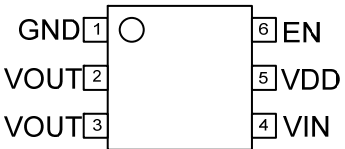


Fig.36 Block diagram

B	VIN	VOUT	VOUT
A	VDD	EN	GND
	1	2	3

BD6529GUL (Bottom view)



BD6528HFV (Top view)

Fig.37 Pin configuration

●Pin description

Pin number	Pin name	Pin function
1 (A3)	GND	Ground
2, 3 (B2, B3)	VOUT	Switch output (connect each pin externally)
4 (B1)	VIN	Switch input
5 (A1)	VDD	Power supply (for switch control and drive circuit)
6 (A2)	EN	Enable input (Active-High Switch on input)

●I/O equivalent circuit

Pin name	Pin number	Equivalent circuit
EN	6 (A2)	
VIN VOUT	4 (B1) 2, 3 (B2, B3)	

●Operation description

1. Switch operation

Each VIN and VOUT pins are connected to MOSFET's drain and source. By setting EN input to High level, the internal charge pump operates and turns on MOSFET.

When MOSFET is turned on, the switch becomes bidirectional characteristics. Consequently, in case of $V_{IN} < V_{OUT}$, the current is flowing from VOUT to VIN.

Since there is no parasitic diode between switch's drain and source, it prevents the reverse current flow from VOUT to VIN during switch off stage.

2. Output discharge circuit

Discharge circuit operates when switch is off. When discharge circuit operates, 70Ω (Typ.) resistor is connected between VOUT pin and GND pin. This discharges the electrical charge quickly.

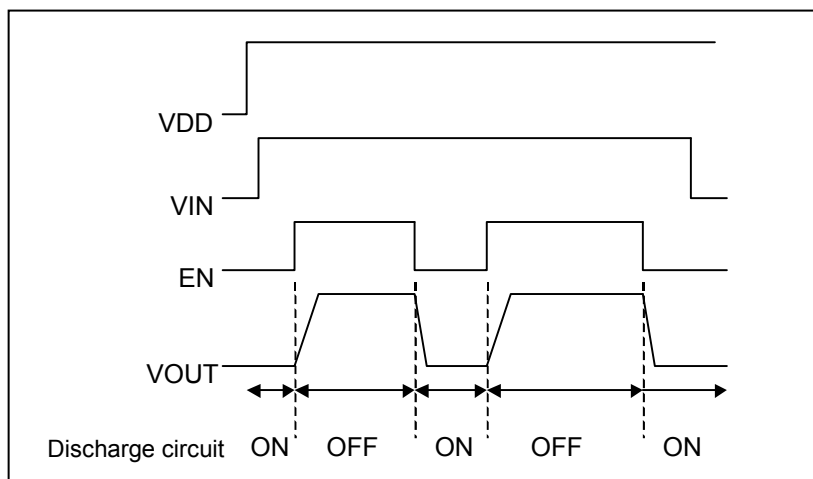


Fig.38 Operation timing

●Application circuit example

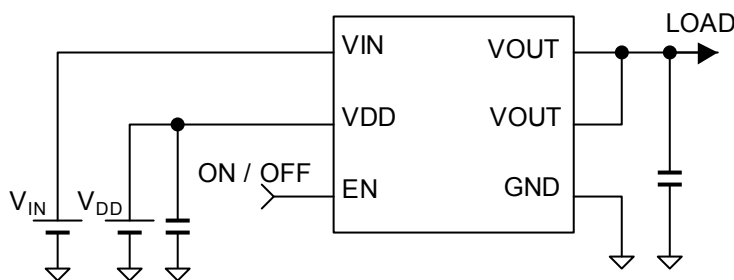


Fig.39 Application circuit example

* This application circuit does not guarantee its operation.

When the external circuit constant, etc. is changed, be sure to consider adequate margins; by taking into account external parts and/or IC's dispersion including not only static characteristics, but also transient characteristics.

●Power dissipation characteristics

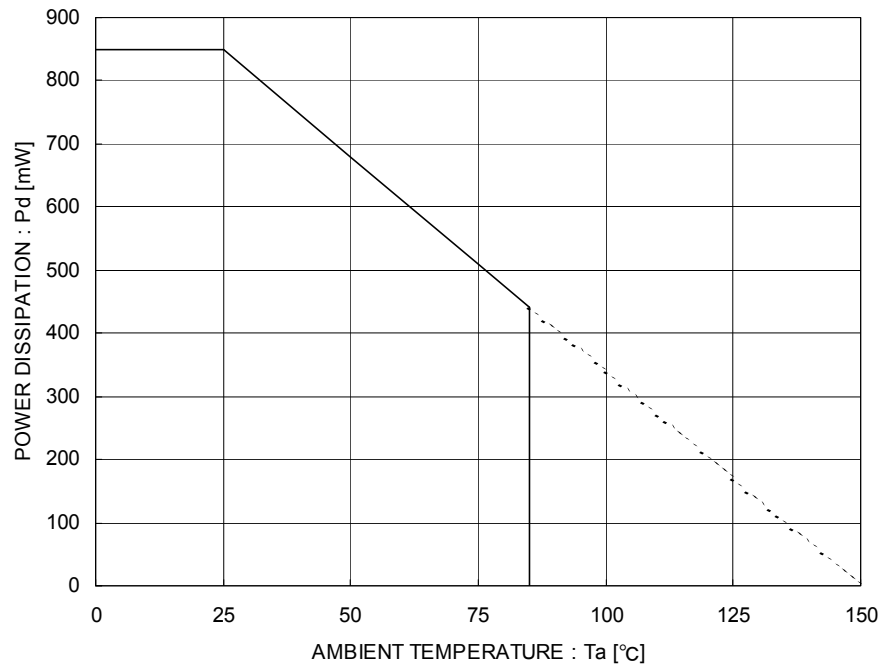


Fig.40 Power dissipation curve (Pd-Ta Curve)
(HVSO6 package)

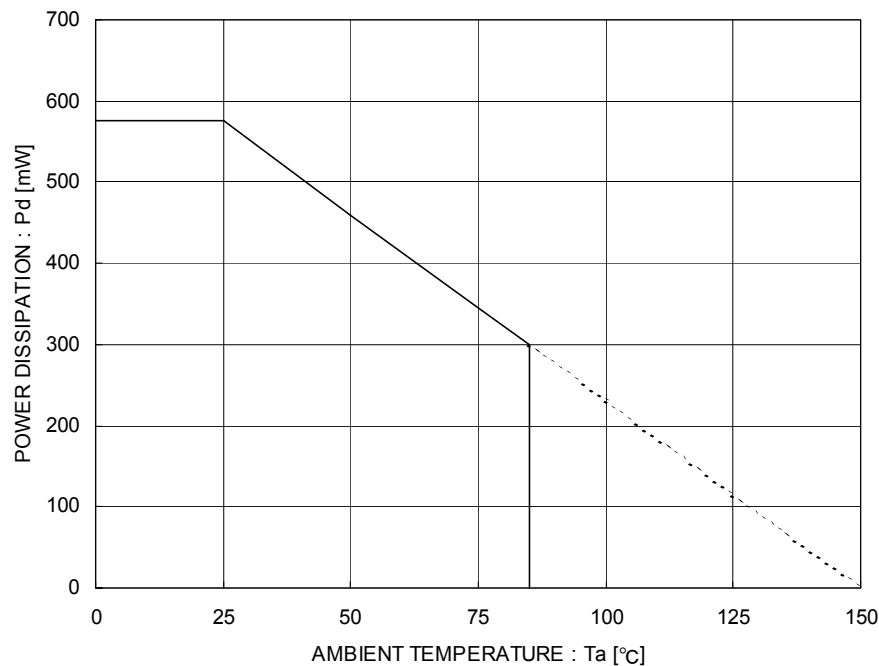


Fig.41 Power dissipation curve (Pd-Ta Curve)
(VCSP50L1 package)

●Notes for use**(1) Absolute Maximum Ratings**

An excess in the absolute maximum ratings, such as supply voltage, temperature range of operating conditions, etc., can break down devices, thus making impossible to identify breaking mode such as a short circuit or an open circuit. If any special mode exceeding the absolute maximum ratings is assumed, consideration should be given to take physical safety measures including the use of fuses, etc.

(2) Power supply and GND line

Design PCB pattern to provide low impedance for the wiring between the power supply and the GND lines. Pay attention to the interference by common impedance of layout pattern when there are plural power supplies and GND lines. Especially, when there are GND pattern for small signal and GND pattern for large current included the external circuits, separate each GND pattern. Furthermore, for all power supply terminals to ICs, mount a capacitor between the power supply and the GND terminal. At the same time, in order to use a capacitor, thoroughly check to be sure the characteristics of the capacitor to be used present no problem including the occurrence of capacity dropout at a low temperature, thus determining the constant.

(3) GND voltage

Make setting of the potential of the GND terminal so that it will be maintained at the minimum in any operating state. Furthermore, check to be sure no terminals are at a potential lower than the GND voltage including an actual electric transient.

(4) Short circuit between terminals and erroneous mounting

In order to mount ICs on a set PCB, pay thorough attention to the direction and offset of the ICs. Erroneous mounting can break down the ICs. Furthermore, if a short circuit occurs due to foreign matters entering between terminals or between the terminal and the power supply or the GND terminal, the ICs can break down.

(5) Operation in strong electromagnetic field

Be noted that using ICs in the strong electromagnetic field can malfunction them.

(6) Input terminals

In terms of the construction of IC, parasitic elements are inevitably formed in relation to potential. The operation of the parasitic element can cause interference with circuit operation, thus resulting in a malfunction and then breakdown of the input terminal. Therefore, pay thorough attention not to handle the input terminals, such as to apply to the input terminals a voltage lower than the GND respectively, so that any parasitic element will operate. Furthermore, do not apply a voltage to the input terminals when no power supply voltage is applied to the IC. In addition, even if the power supply voltage is applied, apply to the input terminals a voltage lower than the power supply voltage or within the guaranteed value of electrical characteristics.

(7) External capacitor

In order to use a ceramic capacitor as the external capacitor, determine the constant with consideration given to a degradation in the nominal capacitance due to DC bias and changes in the capacitance due to temperature, etc.

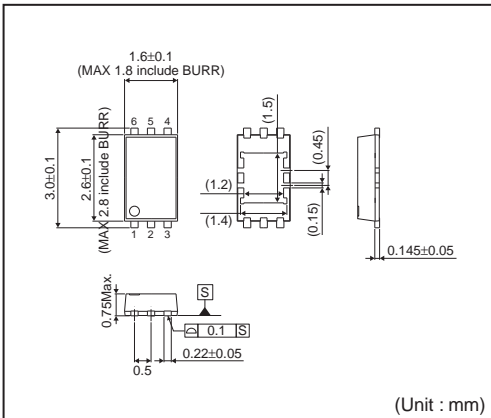
(8) Thermal design

Perform thermal design in which there are adequate margins by taking into account the power dissipation (PD) in actual states of use.

●Ordering part number

<table><tr><td>B</td><td>D</td></tr></table>	B	D	<table><tr><td>6</td><td>5</td><td>2</td><td>8</td></tr></table>	6	5	2	8	<table><tr><td>H</td><td>F</td><td>V</td></tr></table> - <table><tr><td>T</td><td>R</td></tr></table>	H	F	V	T	R
B	D												
6	5	2	8										
H	F	V											
T	R												
Part No.	Part No. 6528 6529	Package HFV: HVSO6 GUL: VCSP50L1	Packaging and forming specification TR: Embossed tape and reel (HVSO6) E2: Embossed tape and reel (VCSP50L1)										

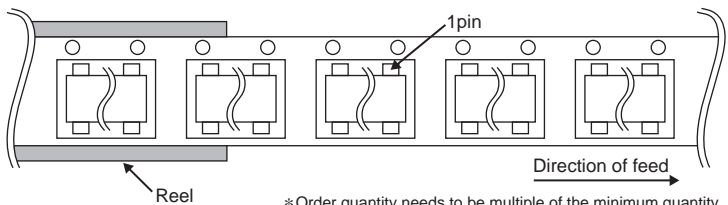
HVSO6



(Unit : mm)

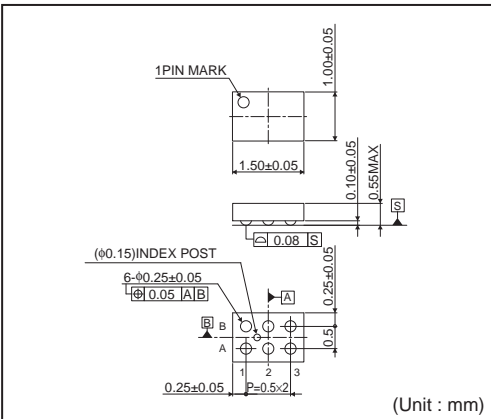
<Tape and Reel information>

Tape	Embossed carrier tape
Quantity	3000pcs
Direction of feed	TR (The direction is the 1pin of product is at the upper right when you hold reel on the left hand and you pull out the tape on the right hand)



* Order quantity needs to be multiple of the minimum quantity.

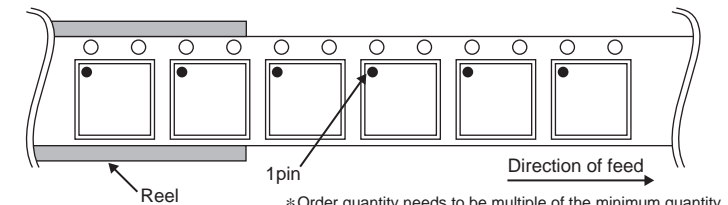
VCSP50L1(BD6529GUL)



(Unit : mm)

<Tape and Reel information>

Tape	Embossed carrier tape (heat sealing method)
Quantity	3000pcs
Direction of feed	E2 (The direction is the 1pin of product is at the upper left when you hold reel on the left hand and you pull out the tape on the right hand)



* Order quantity needs to be multiple of the minimum quantity.

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The Products are not designed or manufactured to be used with any equipment, device or system which requires an extremely high level of reliability the failure or malfunction of which may result in a direct threat to human life or create a risk of human injury (such as a medical instrument, transportation equipment, aerospace machinery, nuclear-reactor controller, fuel-controller or other safety device). ROHM shall bear no responsibility in any way for use of any of the Products for the above special purposes. If a Product is intended to be used for any such special purpose, please contact a ROHM sales representative before purchasing.

If you intend to export or ship overseas any Product or technology specified herein that may be controlled under the Foreign Exchange and the Foreign Trade Law, you will be required to obtain a license or permit under the Law.



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More detail product informations and catalogs are available, please contact us.

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